



## Features

- Shorter recovery time
- High speed switching
- High surge current capability
- Enabling higher frequency and increased power density
- System efficiency improvement
- System cost and size savings due to the reduced cooling requirements

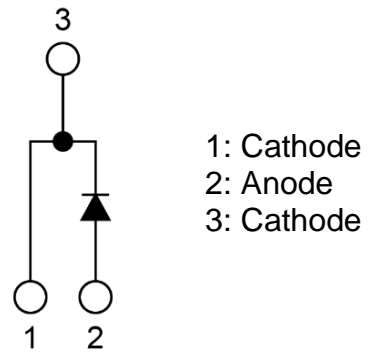
## Outline (TO252-2L)



## Applications

- Power Factor Correction in SMPS
- Solar inverter
- Uninterruptible Power Supply
- Motor Drives
- Data Center

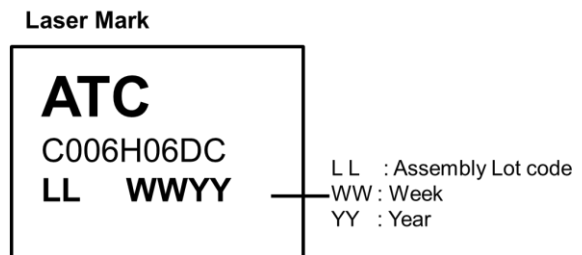
## Circuit Diagram



## Mechanical Characteristics

- TO252 package
- Halogen Free
- Pb free lead plating ; RoHS compliant
- Packaging: Embossed Tape

## Marking Diagram





650V / 6A

AEC006H06DC

SiC Schottky Barrier Diode

ACTRON TECHNOLOGY CORP.

## Parameter and Specification

### Absolute Maximum Rating<sup>(1)</sup>

Parameter	Symbol	Condition	Value	Unit
Repetitive peak reverse voltage	$V_{RM}$	$T_c=25^{\circ}C$	650	V
Continue forward current	$I_F$	$T_c=135^{\circ}C$	6	A
Surge non-repetitive forward current , sine half-wave	$I_{FSM}$	$T_c=25^{\circ}C$ , $t_p=10ms$ , Sine half wave	52	A
		$T_c=110^{\circ}C$ , $t_p=10ms$ , Sine half wave	41	
Surge repetitive forward current	$I_{FRM}$	$T_c=25^{\circ}C$ , $t_p=10ms$ , Sine half wave	25	A
$I^2t$ value	$\int I^2t$	$T_c=25^{\circ}C$ , $t_p=10ms$ , Sine half wave	13	$A^2s$
Total power dissipation	$P_D$	$T_c=25^{\circ}C$	85	W
		$T_c=110^{\circ}C$	37	
Junction temperature	$T_j$		175	$^{\circ}C$
Storage temperature	$T_{STG}$		-55 ~ 175	$^{\circ}C$

Note :

(1) Exceeding these ratings may damage the device.

### Thermal Characteristics

Parameter	Symbol	Condition	Typ.	Unit
Thermal resistance	$\theta_{jc}$	Junction - Case	2.9	$^{\circ}C / W$

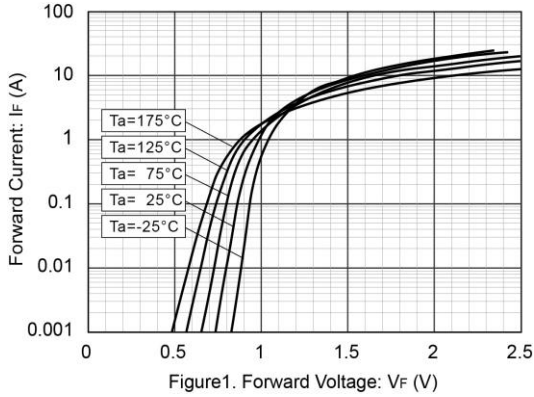
**Electrical Characteristics**

Characteristic	Symbol	Condition	MIN	TYP	MAX	Unit
DC reverse voltage	$V_{DC}$	$T_j = 25^{\circ}C, I_R = 30 \mu A$	650	-	-	V
Forward voltage	$V_F$	$T_j = 25^{\circ}C, I_F = 6A$	-	1.35	1.5	V
		$T_j = 150^{\circ}C, I_F = 6A$	-	1.6	-	
		$T_j = 175^{\circ}C, I_F = 6A$	-	1.7	-	
Reverse current	$I_R$	$T_j = 25^{\circ}C, V_R = 650V$	-	1.2	30	uA
		$T_j = 150^{\circ}C, V_R = 650V$	-	4.8	-	
		$T_j = 175^{\circ}C, V_R = 650V$	-	9	-	
Total capacity charge	$Q_C$	$T_j = 25^{\circ}C, V_R = 400V,$ $di/dt = 350A/us$	-	15	-	nC
Total capacitance	$C_{TOT}$	$T_j = 25^{\circ}C, V_R = 1V,$ $F = 1MHz$	-	240	-	pF
		$T_j = 25^{\circ}C, V_R = 400V,$ $F = 1MHz$	-	26	-	
		$T_j = 25^{\circ}C, V_R = 650V,$ $F = 1MHz$	-	25	-	
Capacitance Stored Energy	$E_C$	$V_R = 400V$	-	2.5	-	$\mu J$

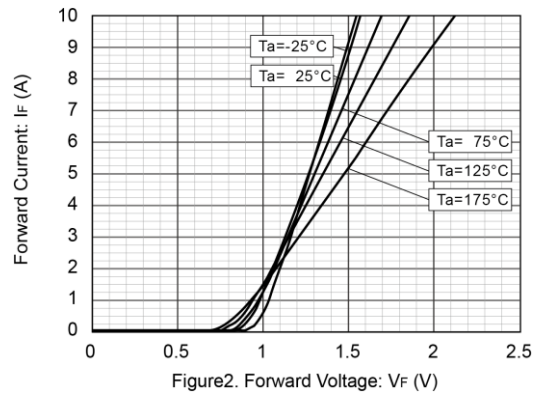


### Electrical Characteristic Curves

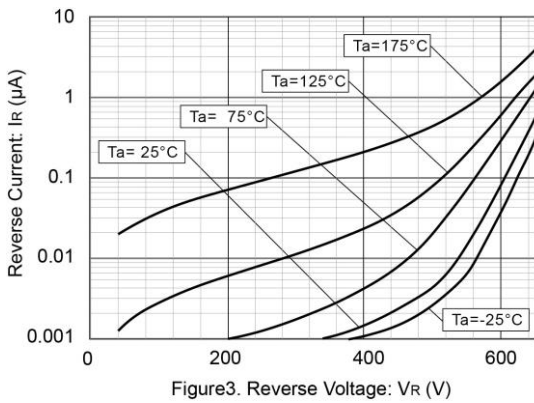
#### V<sub>F</sub> – I<sub>F</sub> Characteristics



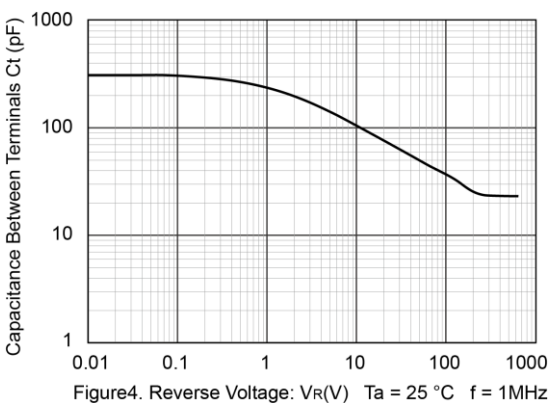
#### V<sub>F</sub> – I<sub>F</sub> Characteristics



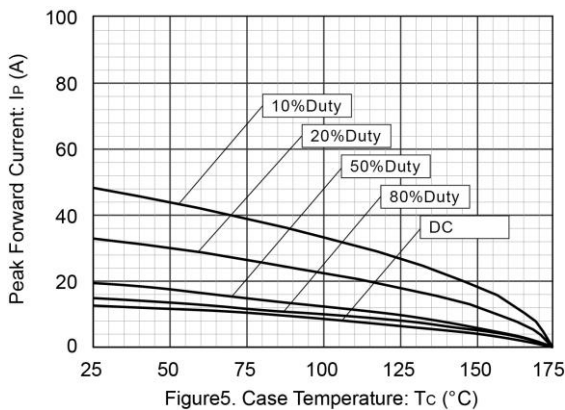
#### V<sub>R</sub> – I<sub>R</sub> Characteristics



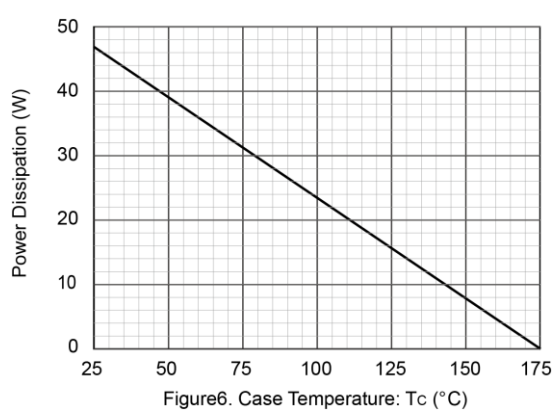
#### V<sub>R</sub> – C<sub>t</sub> Characteristics



#### Maximum I<sub>P</sub> – T<sub>C</sub> Characteristics

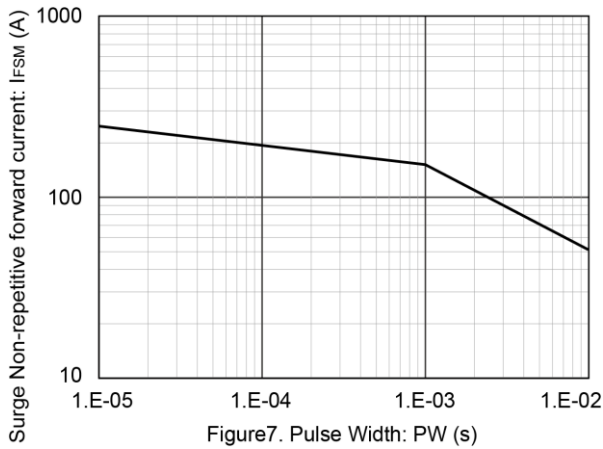


#### Power Dissipation

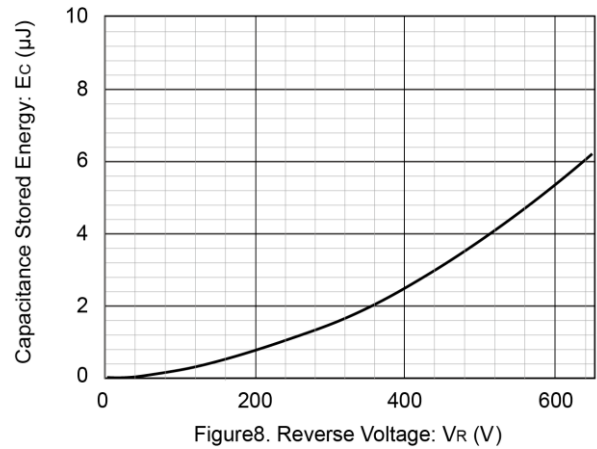




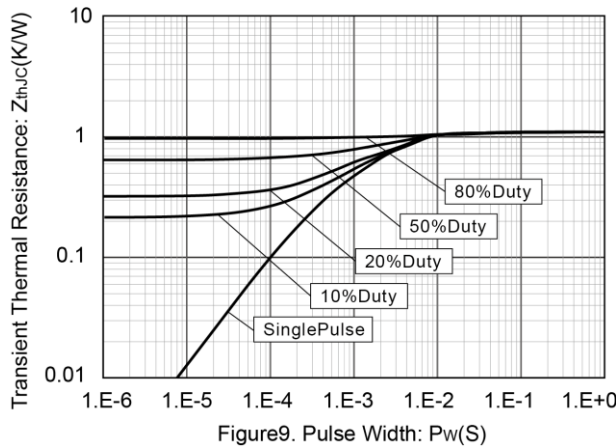
**I<sub>FSM</sub> – Pw Characteristics**



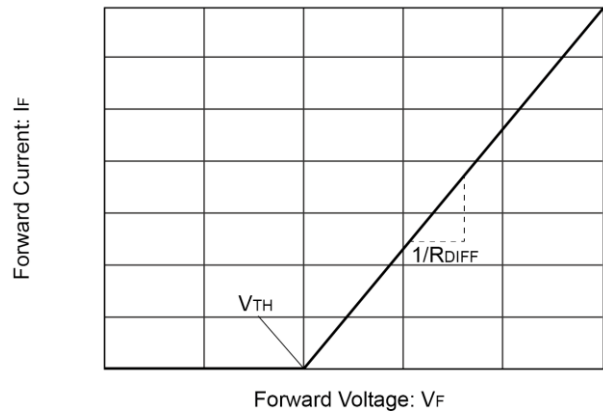
**E<sub>c</sub> – V<sub>R</sub> Characteristics**



**Typical Transient Thermal Resistance vs. Pulse Width**



**Simplified Forward Characteristic**



$$V_F = V_{TH} + R_{DIFF} \times I_F$$

**Threshold Voltage (V<sub>TH</sub>):**

$$V_{TH}(T_j) = -0.0019 \times T_j + 0.78 [V]$$

**Differential Resistance (R<sub>DIFF</sub>):**

$$R_{DIFF}(T_j) = A \times T_j^2 + B \times T_j + C [\Omega]$$

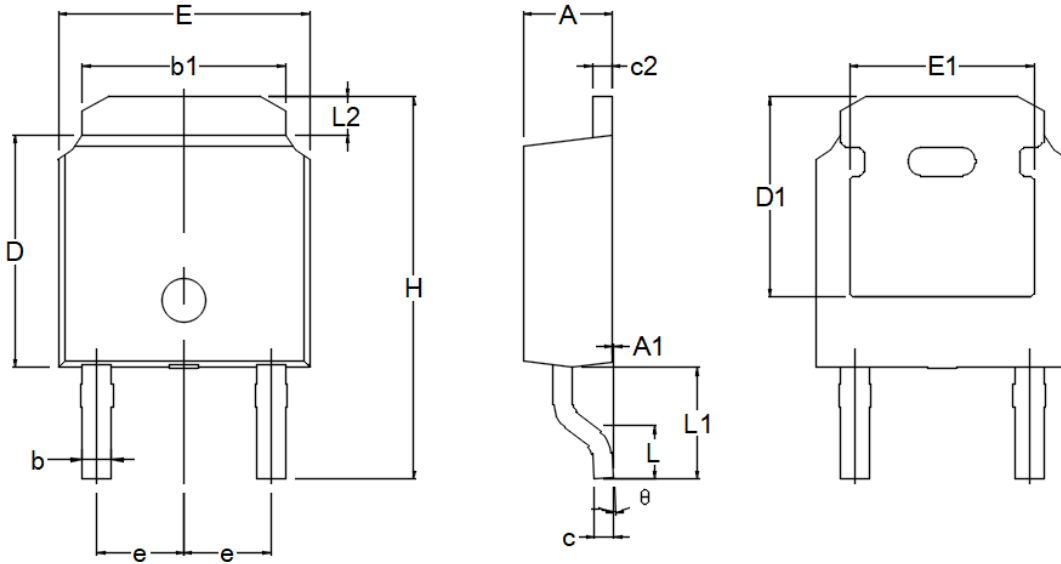
$$A = 2.0 \times 10^{-6}$$

$$B = 4.0 \times 10^{-4}$$

$$C = 7.68 \times 10^{-2}$$



Package Outline.



Unit : mm

SYMBOL	DIMENSIONAL REQMTS		
	MIN	NOM	MAX
E	6.40	6.60	6.731
L	1.40	1.52	1.77
L1	2.743 REF		
L2	0.89	--	1.27
D	6.00	6.10	6.223
H	9.40	10.00	10.40
b	0.64	0.76	0.88
b1	5.21	5.34	5.46
e	2.286 BSC		
A	2.20	2.30	2.38
A1	0	--	0.127
c	0.46	0.50	0.60
c2	0.46	0.50	0.58
D1	5.21	--	--
E1	4.40	--	--
θ	0°	--	10°